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METHOD OF MANUFACTURING FINE METAL PARTICLES, ~~SUBSTANCE~~
~~CONTAINING FINE METAL PARTICLES, AND PASTE SOLDER COMPOSITION~~

CROSS-REFERENCE TO RELATED APPLICATIONS

5 This application claims priority to the United States Patent Application Serial
Number 10/106,646 filed on March 26, 2002, ^{abandoned,} which is a U.S. National Phase of Japan
Application Number 2001-092273 filed March 28, 2001; Japan Application Number
2001-288778 filed September 21, 2001; and Japan Application Number 2001-395566 filed
December 27, 2001.

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BACKGROUND OF THE INVENTION

The present invention relates to a method of manufacturing fine metal particles
such as solder particles, to a fine metal particles-containing substance containing such fine
metal particles, and to a paste solder composition comprising such a fine metal
15 particles-containing substance.

In recent years, concomitant with an increasing trend to multi-functionalize the
wiring board of electronic devices as well as with an increasing trend of miniaturization, i.e.
the reduction of the size and weight of electronic devices, a surface mounting technique
has now been quickly advanced, so that it is now desired, for the purpose of realizing a
20 high density packaging such as the surface mounting of electronic device, to develop a
solder paste or other kinds of soldering materials and a soldering method, which are not